



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
	90mΩ @ V _{GS} = 4.5V	2.8A
20V	120mΩ @ V _{GS} = 2.5V	2.4A

Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP, and is ideal for use in:

- Backlighting
- Power Management Functions
- **DC-DC Converters**
- Motor Control

Features and Benefits Low On-Resistance

- Low Input Capacitance
- Fast Switching Speed
- **ESD Protected Gate**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

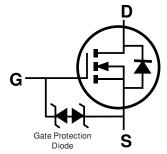
Mechanical Data

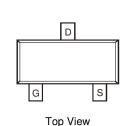
- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Terminals Connections: See Diagram Below
- Weight: 0.009 grams (Approximate)











Internal Schematic

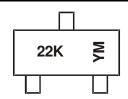
Ordering Information (Note 5)

Part Number	Case	Packaging
DMG2302UKQ-7	SOT23	3,000/Tape & Reel
DMG2302UKQ-13	SOT23	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + CI) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



22K = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: F = 2018) M = Month (ex: 9 = September)

Date Code Key

Year	2015		2016	2017		2018	2019)	2020	2021		2022
Code	С		D	E		F	G		Н			J
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	g Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	20	V
Gate-Source Voltage		V_{GSS}	±12	V
Continuous Drain Current (Note 7) V _{GS} = 4.5V	ΙD	2.8 2.2	Α	
Maximum Continuous Body Diode Forward Curre	ent (Note 7)	I _S	1.1	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle =	1%)	I _{DM}	12	A

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)		P_{D}	0.66	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	192	°C/W
Total Power Dissipation (Note 7)		P_{D}	1.1	W
Thermal Resistance, Junction to Ambient (Note 7)	Steady State	$R_{\theta JA}$	115	°C/W
Operating and Storage Temperature Range		$T_{J_1}T_{STG}$	-55 to +150	°C

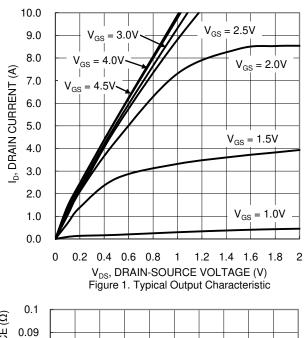
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

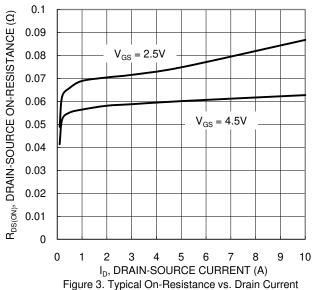
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)	Symbol	IVIIII	тур	IVIAX	Offic	rest condition
Drain-Source Breakdown Voltage		20	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	BV _{DSS}	_	_	10	μΑ	$V_{DS} = 16V, V_{GS} = 0V$
Gate-Source Leakage	Igss	_	_	±10	μΑ	V _{GS} = ±10V, V _{DS} = 0V
ON CHARACTERISTICS (Note 8)	1000		I		, r-	1140 2111, 120 11
Gate Threshold Voltage	$V_{GS(TH)}$	0.3	0.6	1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Chatia Duain Causaa On Danistanaa			61	90	0	$V_{GS} = 4.5V, I_D = 3.6A$
Static Drain-Source On-Resistance	R _{DS(ON)}	_	80	120	mΩ	$V_{GS} = 2.5V, I_D = 3.1A$
Diode Forward Voltage	V_{SD}		0.7	1.2	V	$V_{GS} = 0V, I_{S} = 1.0A$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance			130	_	pF	101/1/
Output Capacitance		l	26	_	pF	$V_{DS} = 10V, V_{GS} = 0V$ - $f = 1.0MHz$
Reverse Transfer Capacitance	C _{rss}	1	18	_	pF	1 = 1.0WH IZ
Gate Resistance	Rg	_	2.7	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	1.4	_	nC	
Total Gate Charge (V _{GS} = 10V)	Qg	_	2.8	_	nC	V 10V I 2.6A
Gate-Source Charge	Q_{gs}	1	0.1	_	nC	$V_{DS} = 10V, I_D = 3.6A$
Gate-Drain Charge	Q_{gd}	_	0.5	_	nC	
Turn-On Delay Time	t _{D(ON)}	_	0.6	_	ns	
Turn-On Rise Time	t _R	_	2.7	_	ns	$V_{DS} = 10V, V_{GS} = 4.5V,$
Turn-Off Delay Time	t _{D(OFF)}	_	4.2	_	ns	$R_g = 1\Omega$, $R_L = 2.78\Omega$
Turn-Off Fall Time	t _F	_	1.7	_	ns	
Reverse Recovery Time	t _{RR}	_	5.3	_	ns	I _F = 3.6A, di/dt = 100A/μs
Reverse Recovery Charge	Q_{RR}	_	0.5	_	nC	I _F = 3.6A, di/dt = 100A/µs

Notes:

- 6. Device mounted on FR-4 PCB with minimum recommended pad layout.
- 7. Device mounted on 1" \times 1" FR-4 PCB with high-coverage 2oz copper, single sided. 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.







and Gate Voltage

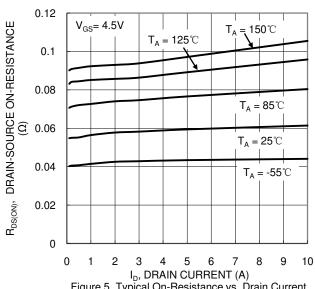
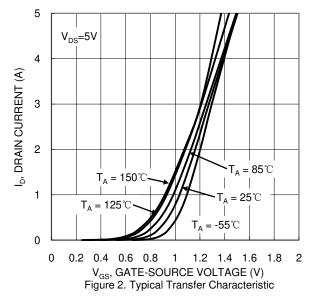
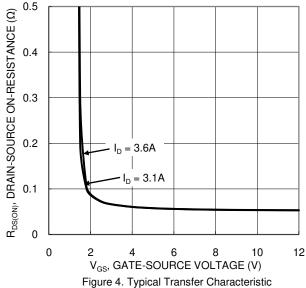


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature





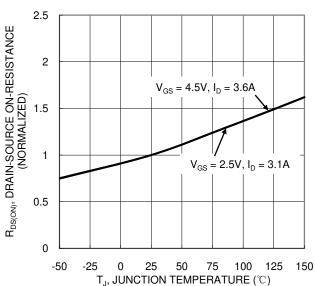
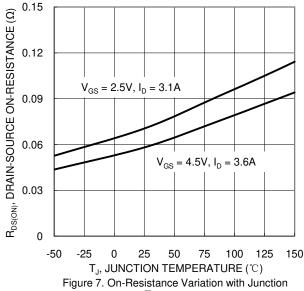


Figure 6. On-Resistance Variation with Junction Temperature





Temperature

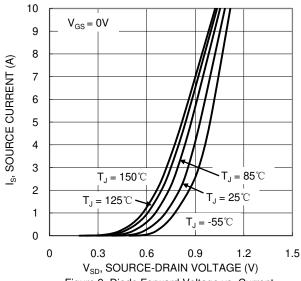


Figure 9. Diode Forward Voltage vs. Current 10 8 6 V_{GS} (V) $V_{DS} = 10V, I_{D} = 3.6A$ 2 0 2 0 0.5 1.5 2.5 3 Q_q (nC) Figure 11. Gate Charge

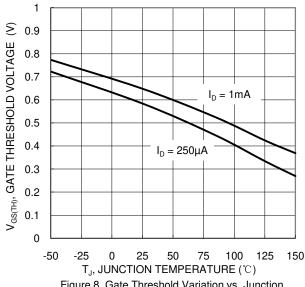
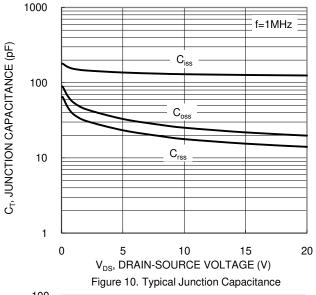
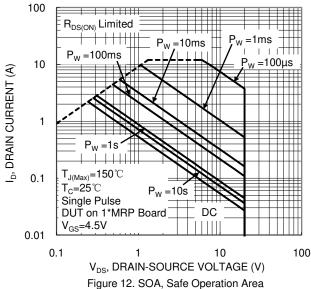
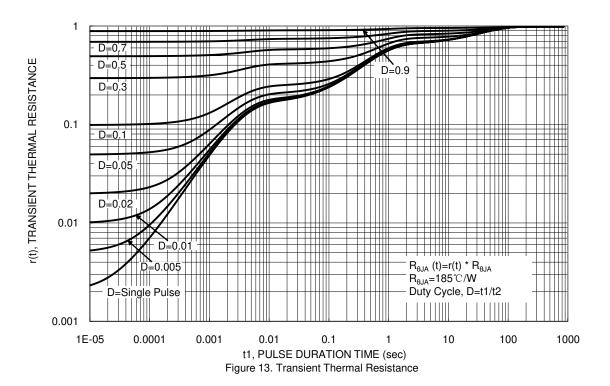


Figure 8. Gate Threshold Variation vs. Junction Temperature





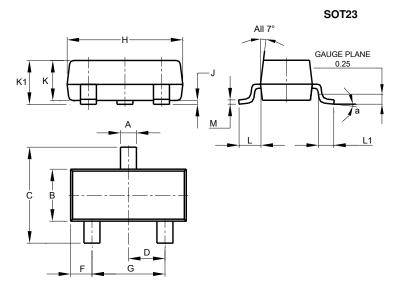






Package Outline Dimensions

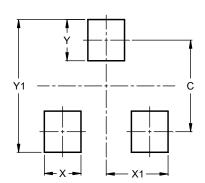
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
C	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
7	0.013	0.10	0.05				
K	0.890	1.00	0.975				
K1	0.903	1.10	1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
М	0.085	0.150	0.110				
а	0°	8°					
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT23

Dimensions	Value (in mm)				
С	2.0				
Х	0.8				
X1	1.35				
Υ	0.9				
Y1	2.9				



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2018, Diodes Incorporated

www.diodes.com